Application Number:	10	10788440					
Filing Date:	01-	01-Mar-2004					
Title of invention:	МЕ	METHOD AND APPARATUS FOR MANUFACTURING BEADS ARRAY CHIP					
First Named Inventor/Applicant Name:	Hic	Hideyuki Noda					
Filer:	Pai	Paul J. Skwierawski/Qiana Graham					
Attorney Docket Number:	103	1021.43570X00					
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Utility under 35 USC 111(a) Filing Fees	1						
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Basic Filing:							
Pages:							
Claims:							
Miscellaneous-Filing:							
Petition:							
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